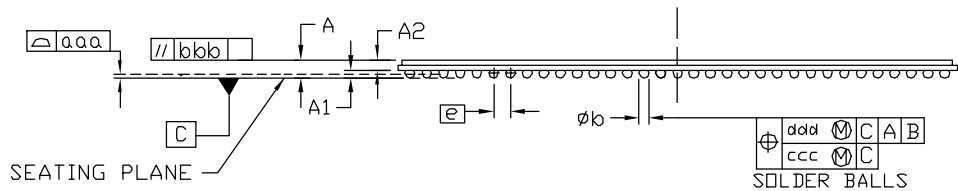
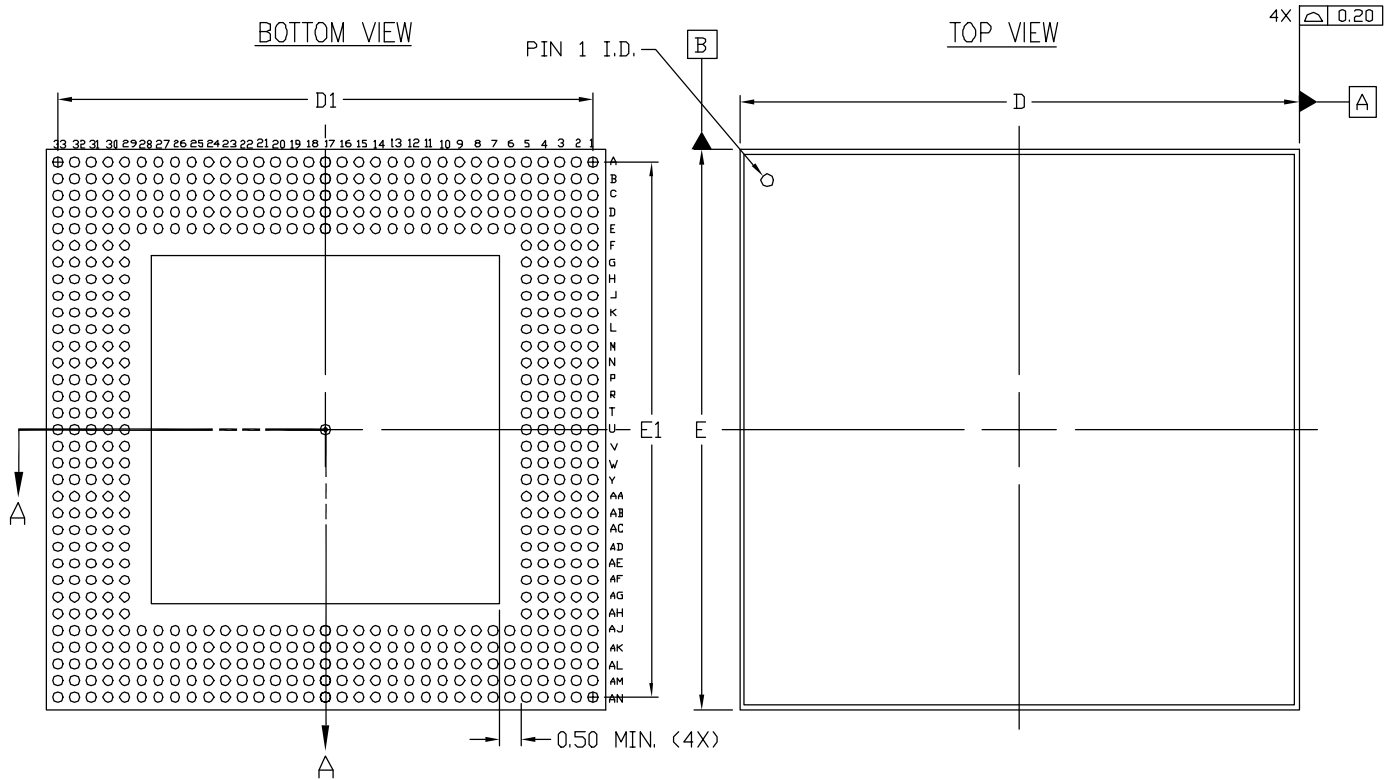
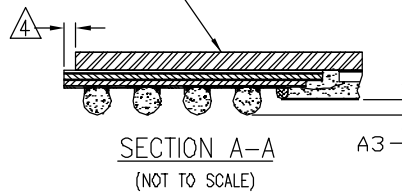


BG560 (DIE DOWN)



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	1.10	1.38	1.70	
A ₁	0.50	0.60	0.70	
A ₂	0.60	$\cancel{\text{---}}$	1.00	
A ₃	0.20	$\cancel{\text{---}}$	$\cancel{\text{---}}$	
D/E	42.50 BSC			
D ₁ /E ₁	40.64 REF.			
e	1.27 BSC			
ϕb	0.60	0.75	0.90	
aaa	$\cancel{\text{---}}$	$\cancel{\text{---}}$	0.20	
ccc	$\cancel{\text{---}}$	$\cancel{\text{---}}$	0.15	
bbb	$\cancel{\text{---}}$	$\cancel{\text{---}}$	0.25	
ddd	$\cancel{\text{---}}$	$\cancel{\text{---}}$	0.30	
M	33			2

METAL HEAT SINK (GROUNDED)



NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE PIN MATRIX SIZE.
3. CONFORMS TO JEDEC MO-192-BAV-1 (DEPOPULATED)

$\triangle 4$ HEAT SINK PULLBACK - 0.375mm MAX.

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SIZE

A

DRAWING NUMBER

OBG0010

REV

03

SCALE NONE

SHEET 2 OF 2